

IN THE CLAIMS

Please amend the claims as follows:

1-21. (Canceled)

22. (New) A fluid ejection device comprising:

a heating element on a substrate surface; and

a cover layer on the substrate surface, the cover layer defining a firing chamber formed about the heating element and defining a nozzle over the firing chamber, wherein the cover layer includes a first layer and a second layer, wherein at least one of the first and second layers includes a dry film.

23. (New) The fluid ejection device of claim 22 wherein the first layer at least partially defines the firing chamber.

24. (New) The fluid ejection device of claim 22 wherein the second layer at least partially defines the nozzle.

25. (New) The fluid ejection device of claim 22 further comprising a third layer between the first and second layers, wherein the third layer at least partially defines the firing chamber.

26. (New) The fluid ejection device of claim 25 wherein the first, second and third layers include dry film.

27. (New) The fluid ejection device of claim 22 wherein the cover layer includes at least two SU8 layers.

28. (New) A fluid ejection device comprising:
 - a resistor on a substrate surface;
 - a first SU8 layer that surrounds the resistor; and
 - a second SU8 layer on the first SU8 layer .
29. (New) The fluid ejection device of claim 28 wherein the second SU8 layer includes a nozzle corresponding to the resistor.
30. (New) The fluid ejection device of claim 28 wherein one of the first and second layer includes a dry film.
31. (New) A method comprising:
 - forming a heating element on a substrate surface;
 - defining a firing chamber formed about the heating element with a first layer on the substrate surface;
 - defining a nozzle over the firing chamber in a second layer; and
 - exposing the substrate surface by offsetting at least one outer edge of the first layer from a respective outer edge of the substrate.
32. (New) The method of claim 31 wherein the first layer and the second layer are SU8 layers.
33. (New) The method of claim 31 further comprising forming at least one of the first or second layer using a lost wax method.

34. (New) A fluid ejection device comprising:
a resistor on a substrate surface; and
a first polymer layer defining a firing chamber formed over the resistor; and
a second polymer layer defining a nozzle over the firing chamber,
wherein at least one of the first and second layers includes a dry film.
35. (New) The fluid ejection device of claim 34 further comprising a third layer between the first and second layers, wherein the third layer at least partially defines the firing chamber.
36. (New) The fluid ejection device of claim 35 wherein the first, second and third layers include dry film.
37. (New) The fluid ejection device of claim 35 wherein the first and second layers are SU8 layers.
38. (New) A fluid ejection device comprising:
a heating element supported by a substrate surface; and
a cover layer supported by the substrate surface, the cover layer defining a firing chamber formed about the heating element and defining a nozzle over the firing chamber, wherein the cover layer includes a plurality of layers, wherein at least one outer edge of the cover layer is offset from a respective outer edge of the substrate to expose the substrate surface.
39. (New) The fluid ejection device of claim 38 wherein the cover layer includes at least two SU8 layers.
40. (New) The fluid ejection device of claim 38 wherein the cover layer includes a countersunk bore about the nozzle.

PRELIMINARY AMENDMENT

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41. (New) The fluid ejection device of claim 38 wherein the cover layer includes a top coat substantially smoothing an upper surface of the cover layer.

42. (New) The fluid ejection device of claim 41 wherein the top coat includes a non-wetting surface.